SN74ABTE16246 11-BIT INCIDENT-WAVE SWITCHING BUS TRANSCEIVER WITH 3-STATE AND OPEN-COLLECTOR OUTPUTS SCBS227J – JULY 1993 – REVISED AUGUST 2003

•	Member of the Texas Instruments Widebus™ Family		DR DL PACH TOP VIEW)	AGE
•	Supports the VME64 ETL Specification	11 OE [$1 \cup 48$] V _{CC} BIAS
•	Reduced TTL-Compatible Input Threshold	11DIR] 11A
	Range	11B] 10DIR
•	High-Drive Outputs (I _{OH} = –60 mA,	GND		GND
	I_{OL} = 90 mA) Support Equivalent 25- Ω	10B] 10A
	Incident-Wave Switching	9В [] 9A
•	V _{CC} BIAS Pin Minimizes Signal Distortion	v _{cc} [7 42] v _{cc}
	During Live Insertion	8BI [9DIR
•	Internal Pullup Resistor on OE Keeps	8BO [9 40] 8A
	Outputs in High-Impedance State During	GND		GND
	Power Up or Power Down	7BO _		7A
•	Distributed V _{CC} and GND Pins Minimize	6BI [7BI
•	High-Speed Switching Noise	6BO		6A
	Equivalent 25- Ω Series Damping Resistor	5BO		5A
•	on B Port	GND		GND
•		4BO L		5BI
•	Bus Hold on Data Inputs Eliminates the	4BI		4A
	Need for External Pullup/Pulldown Resistors	V _{CC}		V _{CC}
	Resistors	3BO L] 3A
des	cription/ordering information	2BI] 3BI
aco		GND		GND
	The SN74ABTE16246 is an 11-bit noninverting	2BO L] 2A
	transceiver designed for asynchronous two-way	1BO		
	communication between buses. This device has	1BI L	24 25] OE
	open-collector and 3-state outputs. The device			

allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated. When \overline{OE} is low, the device is active.

The B port has an equivalent $25-\Omega$ series output resistor to reduce ringing. Active bus-hold inputs on the B port hold unused or floating inputs at a valid logic level.

The A port provides for the precharging of the outputs via $V_{CC}BIAS$, which establishes a voltage between 1.3 V and 1.7 V when V_{CC} is not connected.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

TA	PACKA	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74ABTE16246DL	ABTE16246
	330F - DL	Tape and reel	SN74ABTE16246DLR	AB1E10240
	TSSOP – DGG	Tape and reel	SN74ABTE16246DGGR	ABTE16246

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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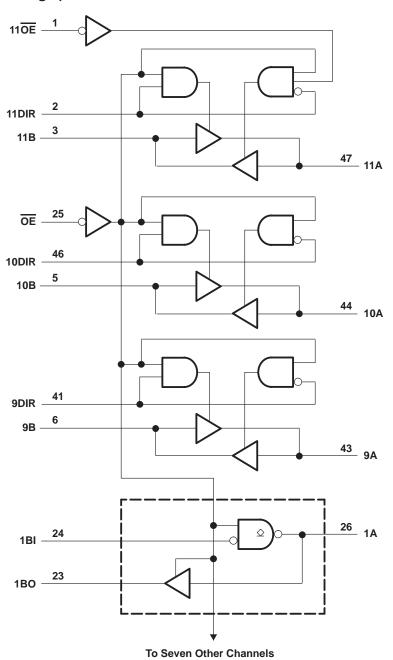
			FUNG		ABLE
		INPUTS			OPERATION
OE	9DIR	10DIR	11DIR	11 <mark>0E</mark>	OFERATION
Н	Х	Х	Х	Х	Isolation
L	Х	Х	Х	Х	1BI–8BI data to 1A–8A bus (OC [†]), 1A–8A data to 1BO–8BO bus
L	L	Х	Х	Х	9A data to 9B bus
L	н	Х	Х	Х	9B data to 9A bus
L	Х	L	Х	Х	10A data to 10B bus
L	Х	Н	Х	Х	10B data to 10A bus
L	Х	Х	L	L	11A data to 11B bus
L	Х	Х	L	Н	11A, 11B isolation
L	Х	Х	Н	Х	11B data to 11A bus

[†]OC = Open-collector outputs



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logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} and V _{CC} BIAS Input voltage range, V _I (except I/O ports) (see Note 1)	\ldots –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, Vo	–0.5 V to 5.5 V
Current into any output in the low state, IO	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	70°C/W
DL package	
Storage temperature range, T _{stg}	. –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT		
V _{CC} , V _{CC} BIAS	Supply voltage		4.5	5	5.5	V		
	High-level input voltage	2			V			
VIH	High-level linput voltage	Except OE	1.6			v		
Ma					0.8	V		
VIL	Low-level input voltage	Except OE			1.4	v		
VOH	High-level output voltage	1A–8A	0		5.5	V		
VI	Input voltage		0		VCC	V		
1		B bus			-12			
ЮН	High-level output current	9A–11A			-64	mA		
1		B bus			12	A		
IOL	Low-level output current	A bus			90	mA		
Δt/Δv	Input transition rise or fall rate	Outputs enabled			10	ns/V		
Тд	Operating free-air temperature	÷	-40		85	°C		

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CC	TEST CONDITIONS					
VIK		V _{CC} = 4.5 V,	lj = –18 mA		-1.2	V		
		V _{CC} = 5.5 V,	I _{OH} = −100 μA		V _{CC} -0.2			
	B port	V _{CC} = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.4				
\/~··		VCC = 4.5 V	$I_{OH} = -12 \text{ mA}$	2		v		
VOH		V _{CC} = 5.5 V,	$I_{OH} = -1 \text{ mA}$		4.5	v		
	9A–11A	V _{CC} = 4.5 V	I _{OH} = -32 mA	2.4				
		VCC - 4.3 V	I _{OH} =64 mA	2				
IOH	1A–8A	V _{CC} = 4.5 V,	V _{OH} = 5.5 V		20	μΑ		
	B port	V _{CC} = 4.5 V	I _{OL} = 1 mA		0.4			
VOL	Броп	VCC = 4.3 V	I _{OL} = 12 mA		0.8	v		
VOL	A port	$\lambda = 45 \lambda$	$V_{CC} = 4.5 V$ $I_{OL} = 64 mA$					
	Apolt	vcc = 4.3 v	I _{OL} = 90 mA		0.9			
V _{hys}				100		mV		
		$\lambda = 45 \lambda$	V _I = 0.8 V	100				
ll(hold)	B port	$V_{CC} = 4.5 V$	V _I = 2 V	-100		μA		
		V _{CC} = 5.5 V,	$V_{I} = 0$ to 5.5 V		±500			
	Control inputs	$V_{CC} = 5.5 V$			±1			
łı	A or B ports	$V_{CC} = 5.5 V, \overline{OE} = V_{CC}$	$V_{I} = V_{CC} \text{ or } GND$		±20	μA		
IOZH‡	9A–11A	V _{CC} = 5.5 V,	$V_{O} = 2.7 V$		10	μA		
IOZL‡	9A–11A	V _{CC} = 5.5 V,	$V_{O} = 0.5 V$		-10	μΑ		
	A port	V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-180	mA		
10	B port	VCC = 5.5 V;	VO = 2.5 V	-25	-90	mA		
loff		V_{CC} = 0, V_{I} or $V_{O} \le 4.5$ V,	$V_{CC}BIAS = 0$		±100	μA		
			Outputs high	28	36			
ICC	A or B ports	$V_{CC} = 5.5 \text{ V}, I_O = 0,$ $V_I = V_{CC} \text{ or GND}$	Outputs low	38	48	mA		
			Outputs disabled	20	32			
	A or B ports $V_{CC} = 5 V, C_L = 50 pF$		OE high	0.02		mA/		
ICCD		$v_{CC} = 5 v, c_{L} = 50 p_{F}$	OE low	0.33		MHz		
Ci	Control inputs	V _I = 2.5 V or 0.5 V		2.5	4	pF		
Cio	I/O ports	V _O = 2.5 V or 0.5 V		4.5	8	pF		

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.



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live-insertion specifications over recommended operating free-air temperature range

PA	RAMETER		TEST CONDITIONS		MIN	түр†	MAX	UNIT
		$V_{CC} = 0$ to 4.5 V,	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V,$	$I_{O(DC)} = 0$		250	700	μA
		$V_{CC} = 4.5 V \text{ to } 5.5 V^{\ddagger},$	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V,$	$I_{O(DC)} = 0$			20	μΑ
Va	Aport		$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V$	1.1	1.5	1.9	V	
VO	A port	$V_{CC} = 0$	V _{CC} BIAS = 4.75 V to 5.25 V		1.3	1.5	1.7	v
	Aport			$V_{O} = 0$	-20		-100	۸
10	A port	$V_{CC} = 0,$	$V_{CC}BIAS = 4.5 V$	V _O = 3 V	20		100	μA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 $V_{CC} = 0.5 V < V_{CC}BIAS$

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V(T	CC = 5 \ A = 25°C	/, ;	MIN	МАХ	UNIT
		(001101)	MIN	TYP	MAX			
^t PLH	A	В	1.5	3.1	4.2	1.5	5.2	ns
^t PHL	A	D	1.5	3.5	4.6	1.5	5.2	115
^t PLH	9B–11B	9A–11A	1.5	3	3.8	1.5	4.5	
^t PHL		9A-11A	1.5	3.2	4	1.5	4.5	ns
^t PLH [§]			1.5	3.2	4	1.5	4.5	
t _{PLH} ¶	1B–8B	1A–8A	7.5	8.9	9.7	7.5	10.3	ns
^t PHL			1.5	3.2	4	1.5	4.5	
^t PZH	OE	9A–11A	2	4.3	5.3	2	6.2	ns
tPZL	UE	1A–11A	2	4.4	5.4	2	6.8	115
^t PZH	OE	В	2	4.3	6	2	7.1	ns
tPZL	UE	В	2	4.5	6.4	2	7.3	115
^t PHZ		9A–11A	2	4.2	5.9	2	6.7	ns
^t PLZ	OE	1A–11A	2	3.5	4.6	2	5.1	115
^t PHZ	OE	В	2.5	4.3	6.2	2.5	7	ne
^t PLZ		D	2	3.6	5	2	5.5	ns

 $\frac{1}{2}$ Measurement point is V_{OL} + 0.3 V.

¶ Measurement point is V_{OL} + 1.5 V.



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extended switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD		CC = 5 V A = 25°C		MIN	МАХ	UNIT
		(001101)		MIN	TYP	MAX			
^t PLH	9B–11B	9A–11A	Rχ = 13 Ω	1.5	3.2	4	1.5	4.8	ns
^t PHL	9 0 -110	34-114	10^{-10}	1.5	3.8	4.7	1.5	5.6	115
^t PHL	1B–8B	1A–8A	Rχ = 13 Ω	1.5	3.3	4.2	1.5	4.8	ns
^t PLH	0D 44D	04 114	Bv 26.0	1.5	3.1	4	1.5	4.6	
^t PHL	9B–11B	9A–11A	Rχ = 26 Ω	1.5	3.5	4.4	1.5	4.9	ns
^t PHL	1B–8B	1A–8A	Rχ = 26 Ω	1.5	3.1	4	1.5	4.4	ns
^t PLH	00.440	1A-8A	D., 50.0	1.5	3	3.8	1.5	4.5	
^t PHL	9B–11B		$R\chi = 56 \Omega$	1.5	3.3	4.2	1.5	4.7	ns
^t PHL	1B–8B	1A–8A	Rχ = 56 Ω	1.5	3	4	1.5	4.4	ns
	В	А	R _X = Open		0.1	0.6		2	
^t sk(p)	А	В	Rχ = Open		0.4	0.8		2	ns
	В	А	Rχ = 26 Ω		0.3	0.8		2	
	В	А	Rχ = Open		0.3	0.7		1.3	
^t sk(o)	А	В	Rχ = Open		0.7	1.1		1.3	ns
	В	А	Rχ = 26 Ω		0.5	1		1.3	
tt [†]	В	A	Rχ = 26 Ω	0.5	0.8	1.5	0.5	1.5	ns
tt‡	A	В	R _X = Open	3.5	5.5	7.3	3.5	7.9	ns

 † t_t is measured between 1 V and 2 V of the output waveform. ‡ t_t is measured between 10% and 90% of the output waveform.

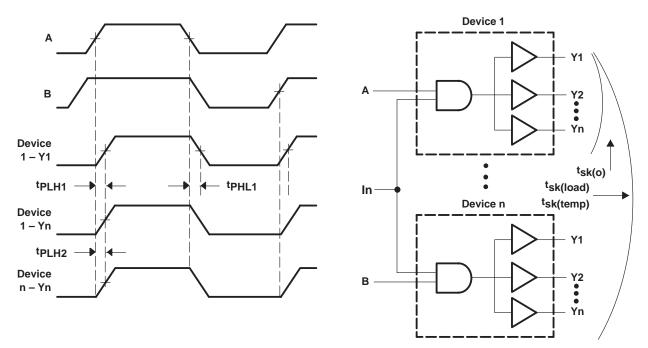
extended output characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	LOAD	MIN MAX	UNIT
+	A	В	V _{CC} = constant,		2.5	ns
^t sk(temp)	В	А	$\Delta T_A = 20^{\circ}C$	R _X = 56 Ω	4	115
^t sk(load)	В	A	V _{CC} = constant, Temperature = constant	R χ = 13, 26, or 56 Ω	4	ns



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PARAMETER MEASUREMENT INFORMATION



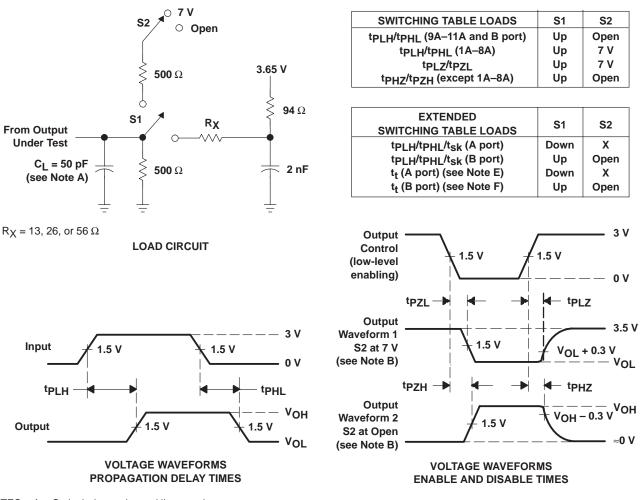
- NOTES: A. Pulse skew, tsk(p), is defined as the difference in propagation-delay times tpLH1 and tpHL1 on the same terminal at identical operating conditions.
 - B. Output skew, tsk(0), is defined as the difference in propagation delay of any two outputs of the same device switching in the same direction (e.g., |tPLH1 - tPLH2|).
 - C. Temperature skew, $t_{sk(temp)}$, is the output skew of two devices, both having the same value of $V_{CC} \pm 1\%$ and with package temperature differences of 20°C.
 - D. Load skew, $t_{sk(load)}$, is measured with R_X in Figure 2 at 13 Ω for one unit and 56 Ω for the other unit.

Figure 1. Voltage Waveforms for Extended Characteristics



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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Cl includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_t is measured between 1 V and 2 V of the output waveform.
 - F. t_f is measured between 10% and 90% of the output waveform.

Figure 2. Load Circuit and Voltage Waveforms





10-Jun-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins	-	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ABTE16246DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246	Samples
SN74ABTE16246DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246	Samples
SN74ABTE16246DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246	Samples
SN74ABTE16246DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



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10-Jun-2014

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ABTE16246DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABTE16246DLR	SSOP	DL	48	1000	367.0	367.0	55.0

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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